**PRESS RELEASE**

**Mex, Switzerland, 14 February 2025**

**BOBST and partners showcase next-level innovation at Turkish roadshow events**

BOBST, along with leading industry partners, held a successful roadshow event in Turkey, demonstrating latest innovations in flexible packaging and labels. The two-day event series, held in Istanbul and Gaziantep in February 2024, brought together packaging industry professionals from across the Turkish market to explore the latest sustainability-focused solutions and digital technologies.

"The strong attendance at both locations reflects the Turkish packaging industry's commitment to innovation and sustainability," said Eric Pavone, BOBST AFMETR Region Business Director. "By bringing together expertise from across the packaging value chain, we demonstrated how collaboration drives progress in sustainable label and packaging solutions. What’s more, we showed how BOBST is at the very cutting edge of progress, and why this is so important for our customers."

The events featured comprehensive technical presentations covering the latest developments in flexible packaging and label production. Key focus areas included BOBST's oneBARRIER technology for recycle-ready mono-material substrates for flexible packaging, as well as digital printing innovations, and the BOBST Connect platform for enhanced connectivity and workflow optimization.

Industry partners including UPM, Reifenhäuser, Michelman, Esko, Sun Chemical and Miraclon shared insights on developments ranging from recyclable paper-based solutions to advanced prepress technologies. The partnership approach highlighted how different technologies can synergize to create more advanced sustainable packaging and label solutions.

"Mirroring global trends, the Turkish market is showing strong interest in technologies that combine sustainability with high performance, without making compromises" said Cihat Ayan, Zone Business Director FP/NMW - Turkey at BOBST. "This roadshow demonstrated how BOBST and our partners are delivering innovations that help converters meet rapidly changing market demands while enhancing sustainability profiles, whether that’s through recyclability, reducing waste or driving down business energy use."

Interactive sessions allowed attendees to explore the latest BOBST technologies, and automated workflow systems. The events also featured live demonstrations of BOBST Connect, showcasing how digitalization and connectivity can combine to enhance production efficiency.

The roadshow reinforced BOBST's commitment to driving innovation in the packaging industry through its four strategic pillars: connectivity, digitalization, automation and sustainability. The strong turnout and engagement from attendees demonstrated the Turkish market's appetite for sustainable packaging solutions and digital transformation.

To learn more about BOBST and its market-leading solutions for the print and packaging industries, please visit [www.bobst.com](http://www.bobst.com).

**About BOBST**

We are one of the world’s leading suppliers of substrate processing, printing and converting equipment and services for the label, flexible packaging, folding carton and corrugated board industries. Our vision is to shape the future of the packaging world based on four pillars: connectivity, digitalization, automation and sustainability.

Founded in 1890 by Joseph Bobst in Lausanne, Switzerland, BOBST has a presence in more than 50 countries, runs 21 production facilities in 12 countries and employs more than 6 300 people around the world. The firm recorded a consolidated turnover of CHF 1.960 billion for the year ended December 31, 2023.

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